



The Keys to Next Generation NAND Interface Technology

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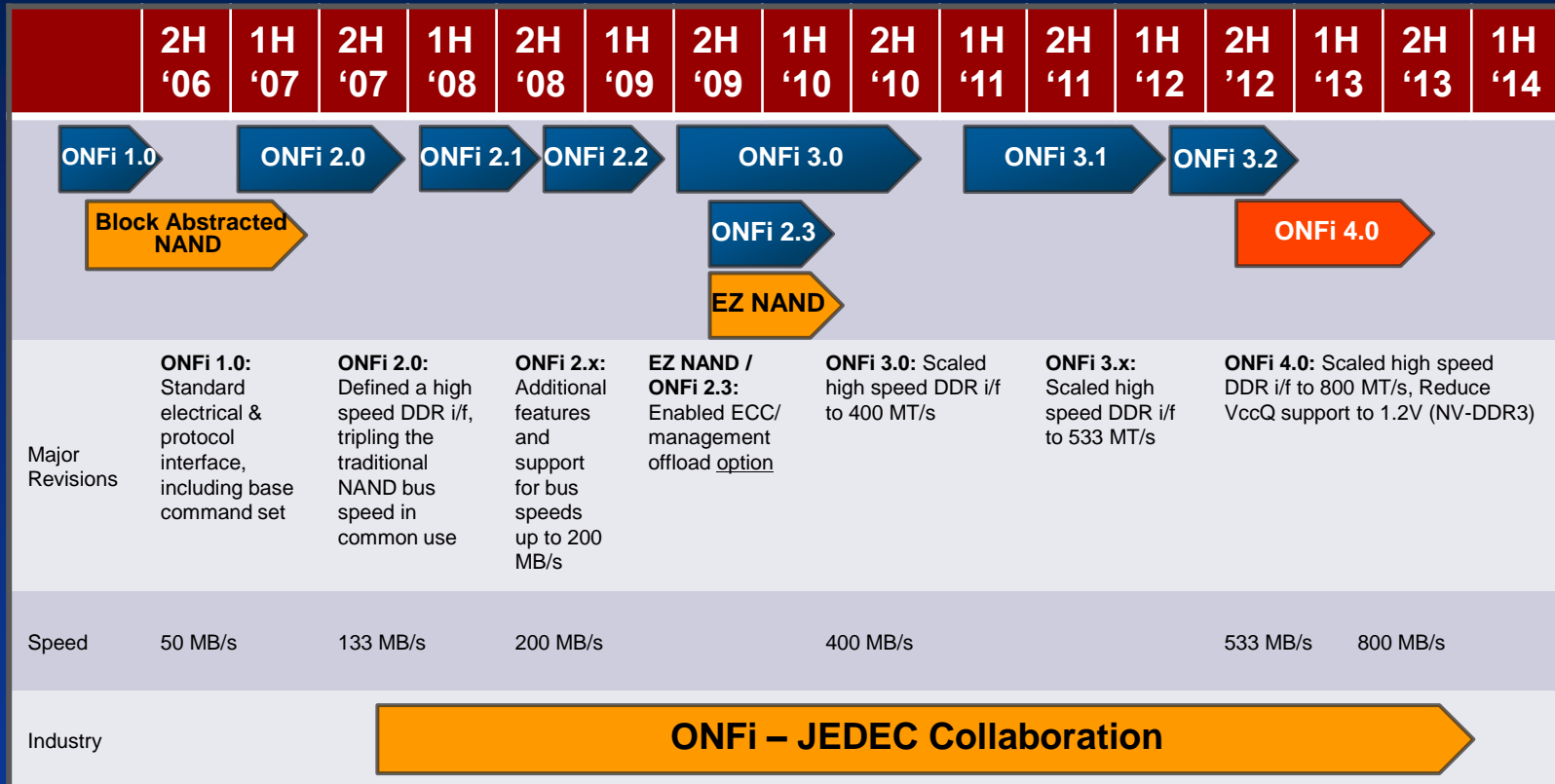
ONFI Specification History

- ONFI formed May 2006
- ONFI 1.0 release December 2006
- ONFI 2.0 release February 2008
- ONFI 2.1 release January 2009
- ONFI 2.2 release October 2009
- ONFI 2.3 release August 2010
- ONFI 3.0 release March 2011
- ONFI 3.1 release September 2012
- ONFI 3.2 release June 2013
- ONFI 4.0 under development





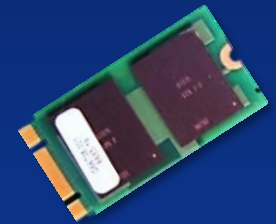
ONFI Workgroup Continues To Produce Results!



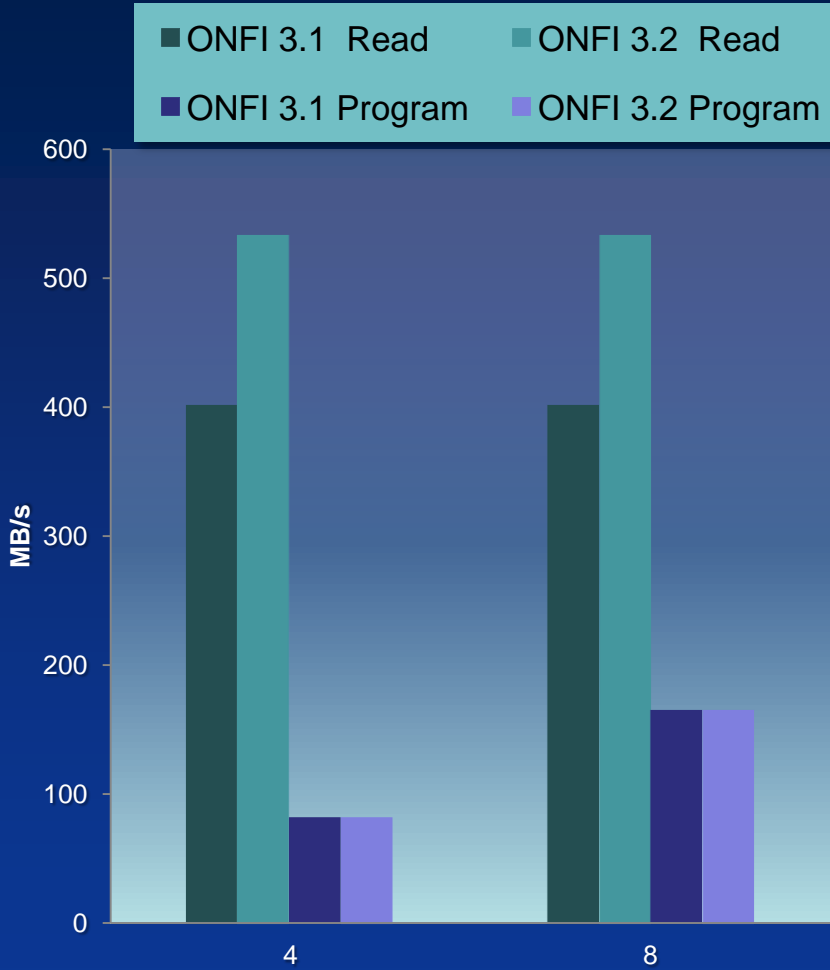
ONFi has and continues to deliver innovation & interoperability enabling faster NAND adoption

ONFI 3.2 - Released June 2013

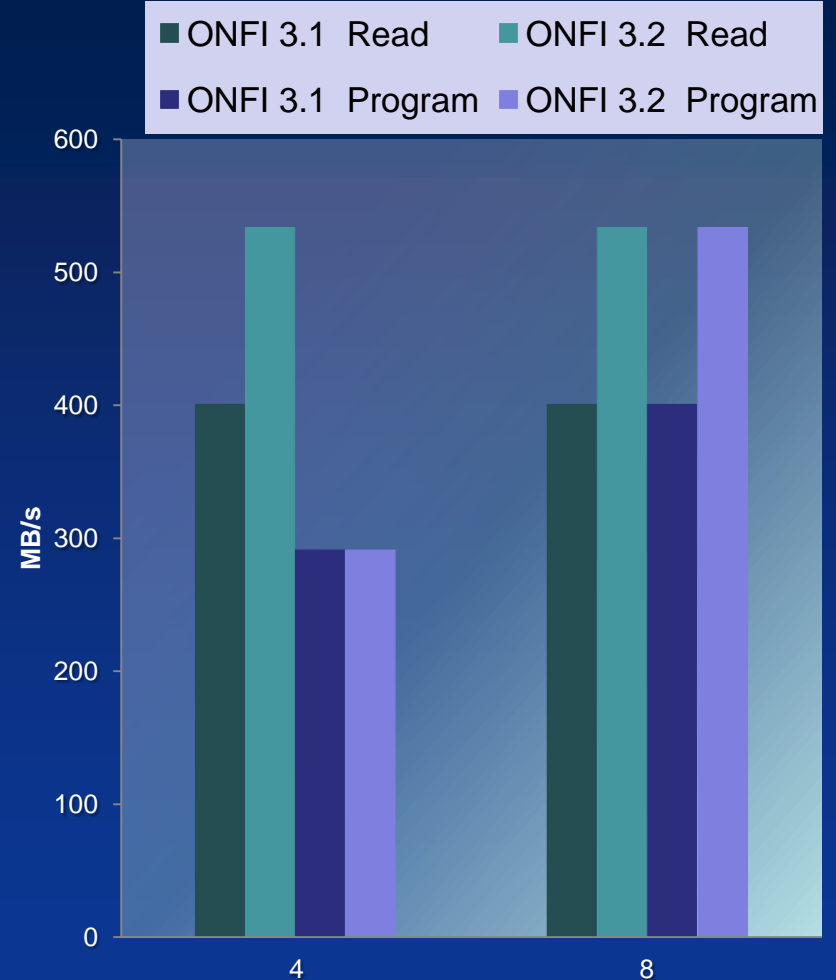
- Enabled 533 MT/s for NV-DDR2
 - Reduced latency
 - Improved sequential performance
- Introduced new 4 channel packages
 - Enables smaller SSD form factors
- Included several ECNs to improve specification



ONFI 3.2 NV-DDR2 I/O Performance



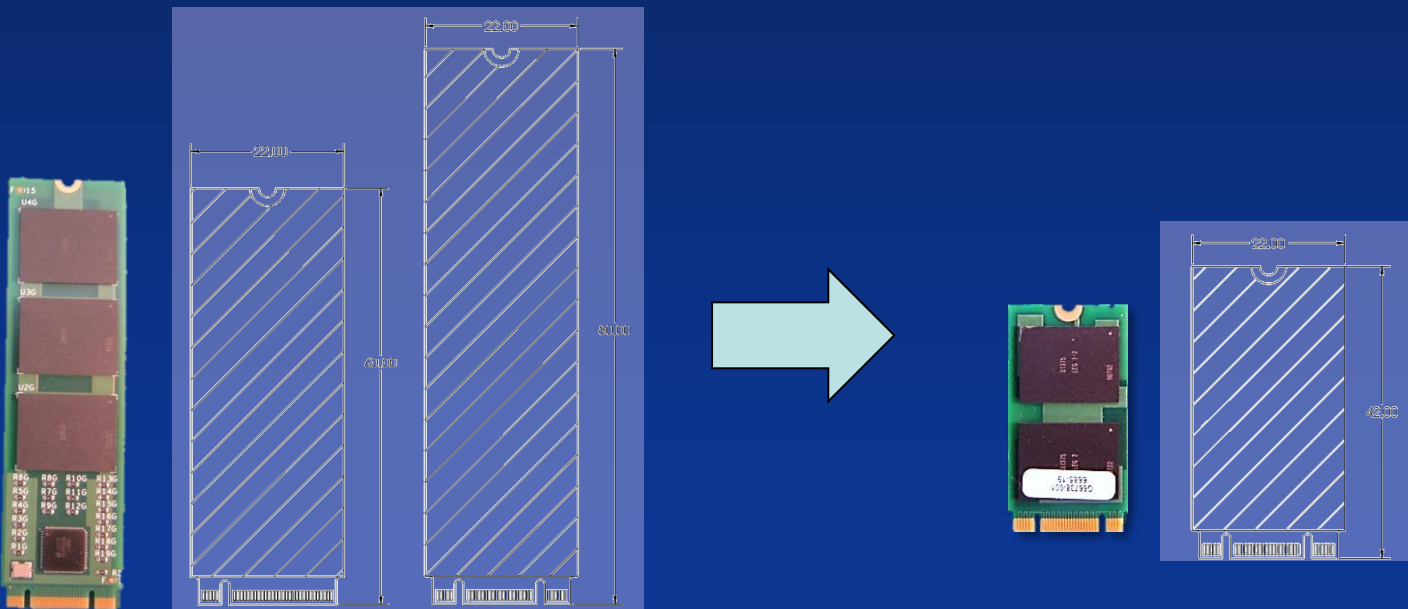
MLC performance with NAND die per channel



SLC performance with NAND die per channel

New Packages Enable Smaller SSD Form Factors

- New 4 channel packages reduce number of required NAND packages
 - 8 Channel controller 4 packages → 2 packages





Requirements for Next Generation

- Improve power I/O consumption
 - Lower I/O voltage
 - Reduced termination requirements
- Increase I/O performance
 - Scale I/O speeds faster as NAND page sizes grow
 - Soft data requirements
- Strive to achieve interoperability between vendors
 - Continue collaboration in JC42.4 ONFI/JEDEC Joint Task Group

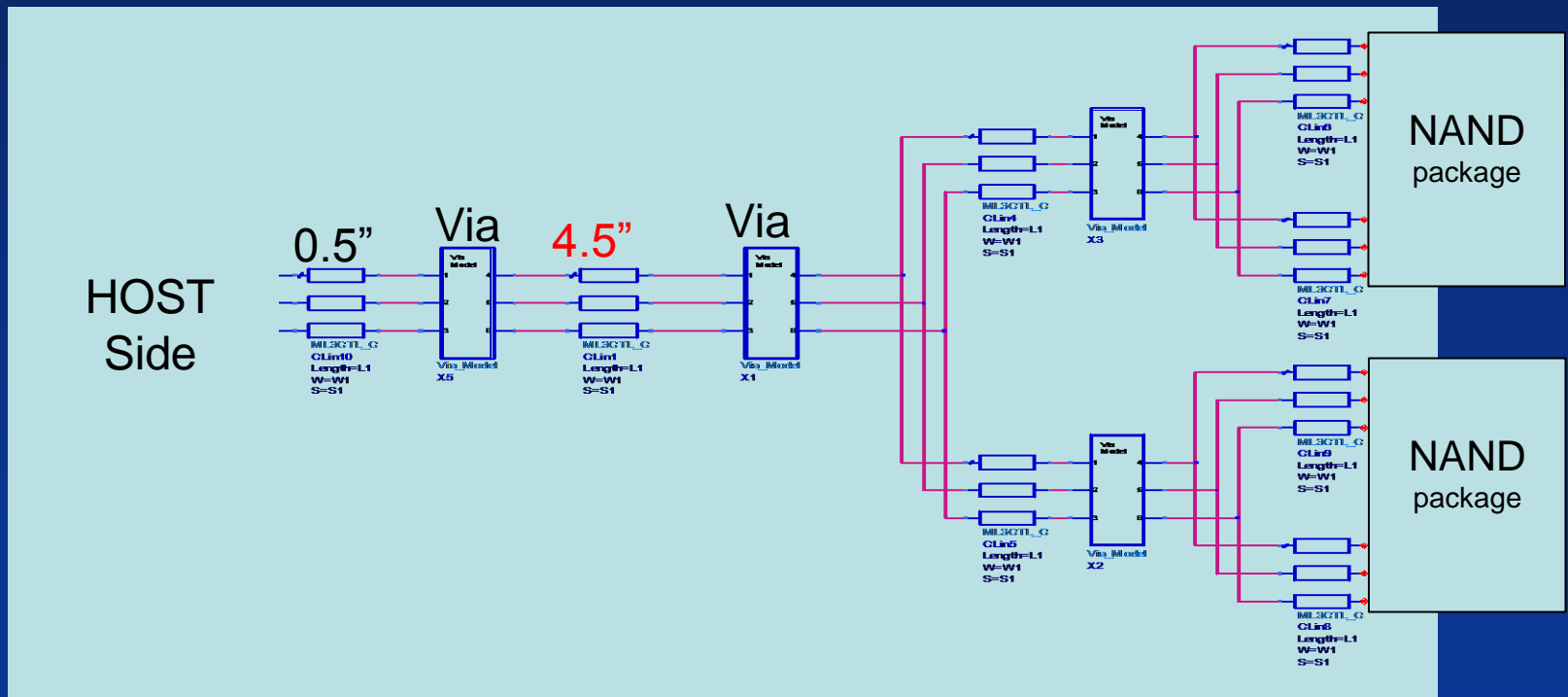
ONFI 4.0 Coming Soon

- Evolutionary
 - Backwards compatible
- Faster I/O speeds
 - Up to 800 MT/s
- New features
 - ZQ calibration
- Reduced I/O voltage
 - 1.2V (NV-DDR3)



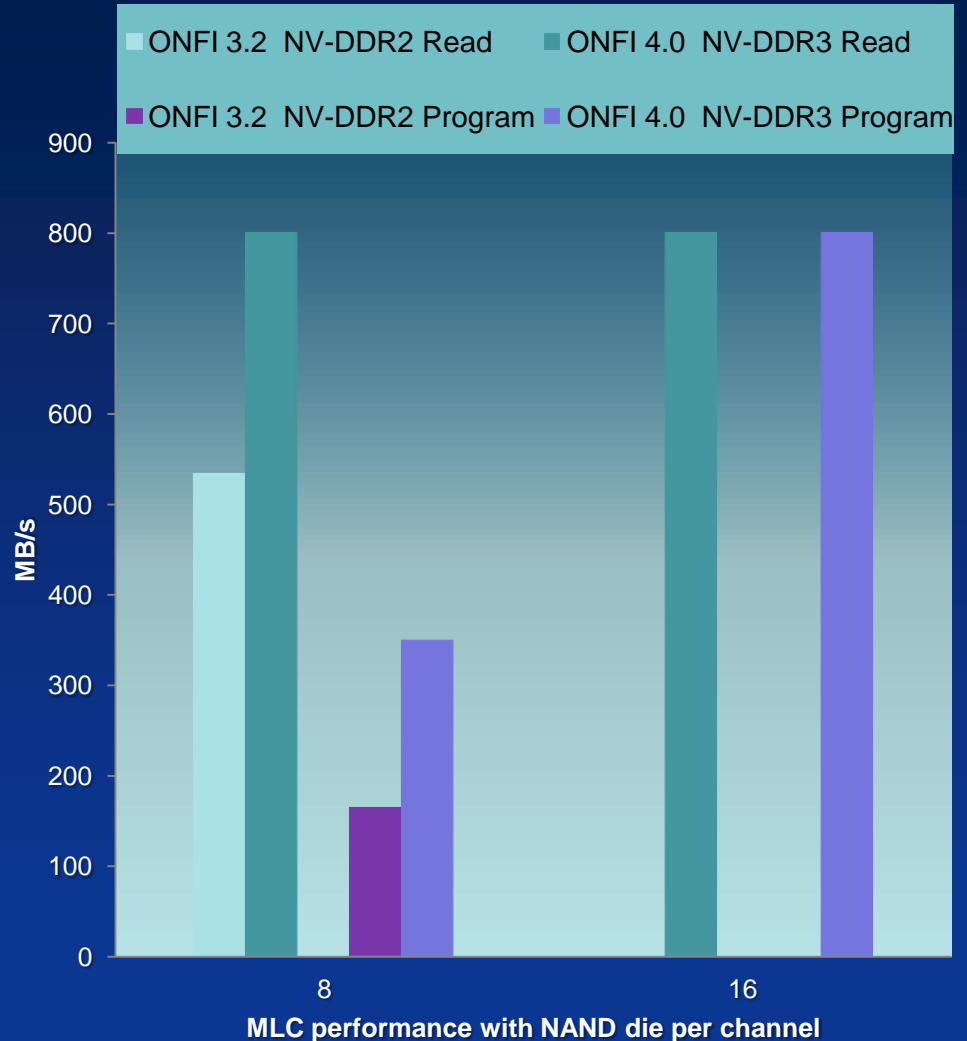
NAND I/O Channel is Diverse

- Short Channel: eMMC, USB, SD, uSD, etc
- Long Channel: SSDs (M.2, 2.5", HHL, etc)
- Lightly loaded, heavily loaded
- Single package, multiple packages per channel



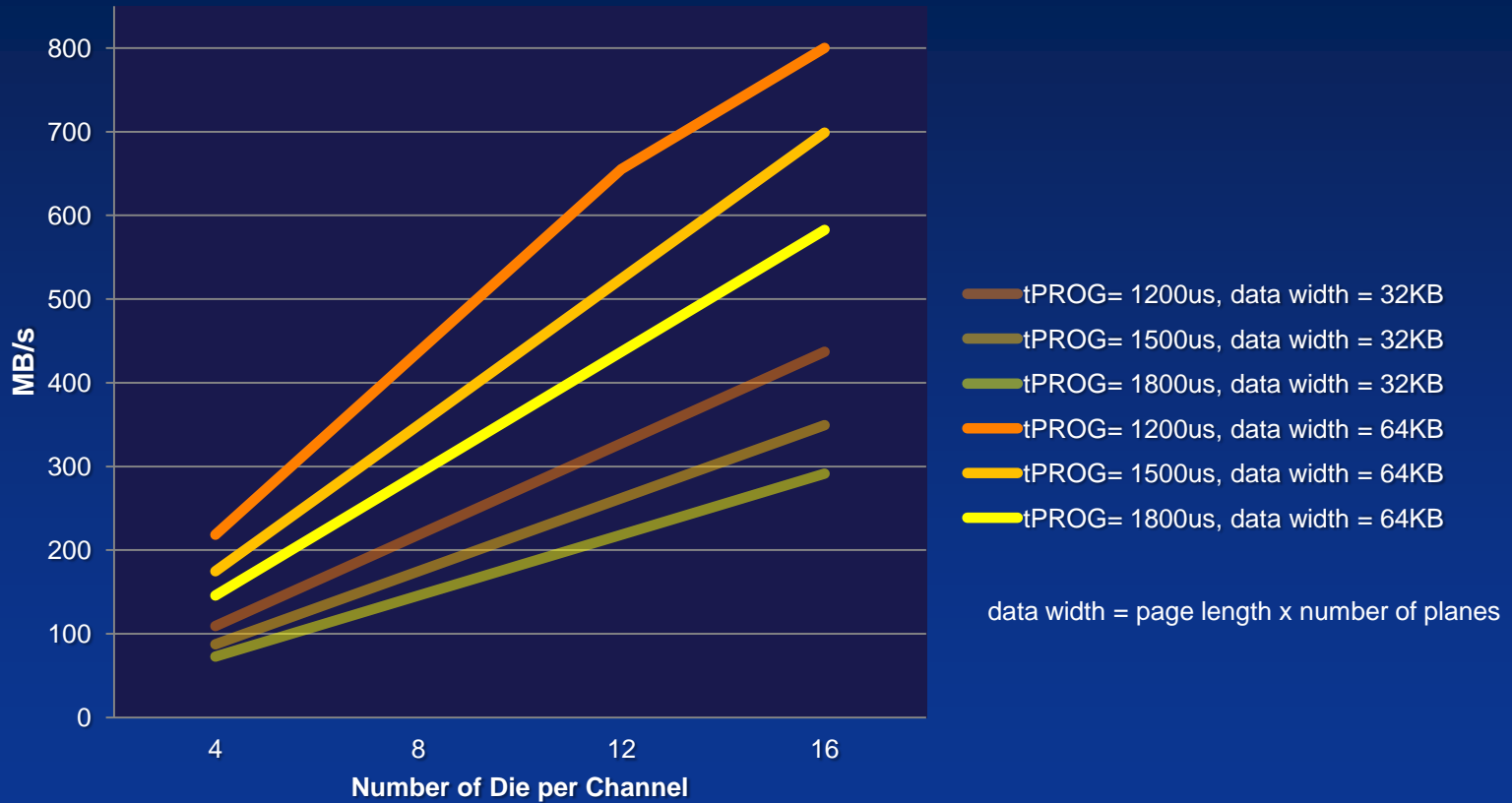
ONFI 4.0 Performance

- Numbers are highly dependent on NAND architecture
 - Page size
 - Number of planes
 - tPROG



Sequential Program Performance

NAND Architecture Dependency



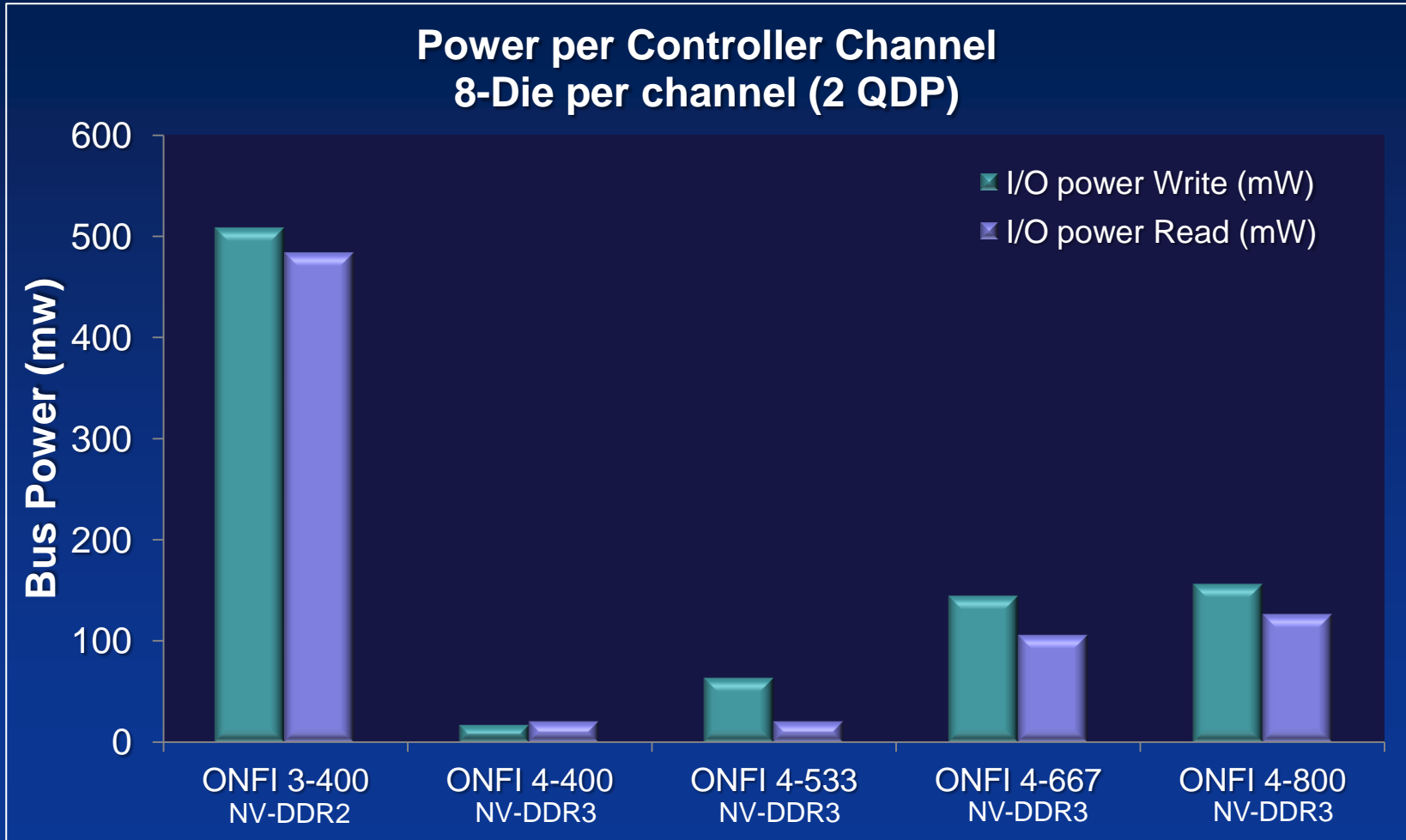
Systems That Use NAND Have Diverse Power Requirements

Application area	Form Factor	System Power Budget
Mobile	MCP	~1W
Client	M.2, 1.8", 2.5"	3W to 5W
Enterprise	2.5", HHHL, FHHL	9W to 25W

System Power Budget is divided among:

- Controller
- NAND
-  Controller to NAND Interface
 - If changes are not made to the interface it will use too much of the power budget

ONFI 4.0 Power Estimates



JC42.4 ONFI/JEDEC Joint Task Group

- ONFI NV-DDR2 interface superset of Toggle Mode
- Discussions ongoing to ensure interoperability between ONFI NV-DDR3 and alternative next generation interfaces

ONFI 4.0 Under Development

- Currently being developed to meet needs of the Future NAND interface
 - Improved power I/O consumption
 - Increased I/O performance
 - Interoperability
- Still time to get involved!
 - Join ONFI: www.onfi.org





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